

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 09-281016
(43)Date of publication of application : 31.10.1997

(51)Int.CI.

G01N 1/28
B28D 5/00
H01L 21/66
// H01L 21/02

(21)Application number : 08-119545

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(22)Date of filing : 18.04.1996

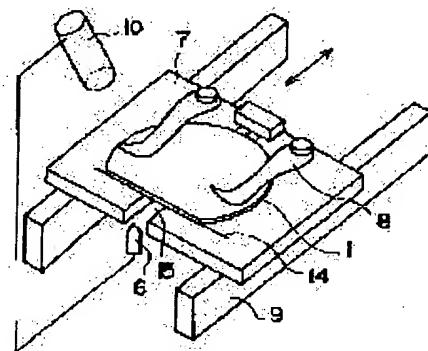
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(54) WAFER SCRIBER

(57)Abstract:

PROBLEM TO BE SOLVED: To obtain a device capable of easily performing cleavage when the cross section of a wafer is observed in order to confirm the process result in the production of a semiconductor by providing a cutter capable of accurately scribing the rear surface of the wafer.

SOLUTION: A sample wafer 1 is fixed with a leaf spring 8 on the stage 7 movable on a rail 9 back and forth. A cutter 6 composed of a diamond needle passes through the groove 15 provided to the stage 7 to scribe the rear surface of the wafer 1. An optical system 10 such as a magnifying glass is provided above the stage 7 and the optical system 10 and the cutter 6 are connected so as to cooperate with each other or so that only the cutter 6 is independently moved. Collimation such as a cross is attached to the visual field of the optical system 10 and, if the cutter 6 is slid so as to be matched with the position to be cut of the surface of the wafer 1, the rear surface of the wafer is scribed at a desired position. If proper tension is applied to the wafer 1, the wafer is cleaved along a scribing line without damaging the sample wafer to perform necessary observation.



LEGAL STATUS

- [Date of request for examination] 07.03.2003
[Date of sending the examiner's decision of rejection]
[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]
[Date of final disposal for application]
[Patent number]
[Date of registration]
[Number of appeal against examiner's decision of rejection]
[Date of requesting appeal against examiner's decision of rejection]
[Date of extinction of right]

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